

in Silicone resin

Solvent based coatings

Evonik Tego formulation No. TOP E 900 9 004

Rev. Number: 01.01

10/20

Function	Product	Producer	PBW
Silicone polyester hybrid resin	SILIKOTOP® E 900	Evonik	16.80
Wetting and dispersing agent	TEGO® Dispers 652	Evonik	1.90
Rheology modifier	BENTONE® SD-2	Elementis	0.10
Molecular sieve powder	SYLOSIV® A 3	Grace	0.50
Rheology modifier	AEROSIL® R 972	Evonik	1.20
Carbon black pigment	Colour Black FW 200	Orion Engineered Carbons	0.10
Quartz	SIKRON® SF6000	HPF The Mineral Engineers	1.50
Kaolin	Polisperse™ 50	Imerys	15.20
Anticorrosive pigment	HEUCOPHOS® CAPP	Sudarshan	6.60
Magnesium silicate	Microtalc™ IT Extra	Elementis	4.40
Titanium dioxide	KRONOS® 2190	KRONOS	14.00
Barium sulfate	EWO	Sachtleben Minerals	15.20
Solvent	Shellsol® D 60	Shell	4.70
Solvent	Methoxypropyl acetate		2.90
Solvent	Butyl acetate		6.90
Grind with a bead mill.			
Catalyst	TIB KAT® 218, 1% in Butyl acetate	TIB Chemicals	1.40
Solvent	Butyl acetate		4.00
Add while stirring.			
Solvent	Butyl acetate		2.60
Adjust to spray viscosity.			
			100.00
Specifications			
Vol.-% Anticorrosive pigment reg. pigment/filler			14.3
PVC in %			57.4
Solids in %			76.0

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